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(12) **United States Design Patent**
Jo et al.

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/110, 182, 184; 361/713, 728, 736, 361/760, 761, 775, 679.01, 820; 257/666, 257/668, 678, 684, 690; 324/71.5, 252; 174/250, 253; 438/64, 65, 66
See application file for complete search history.

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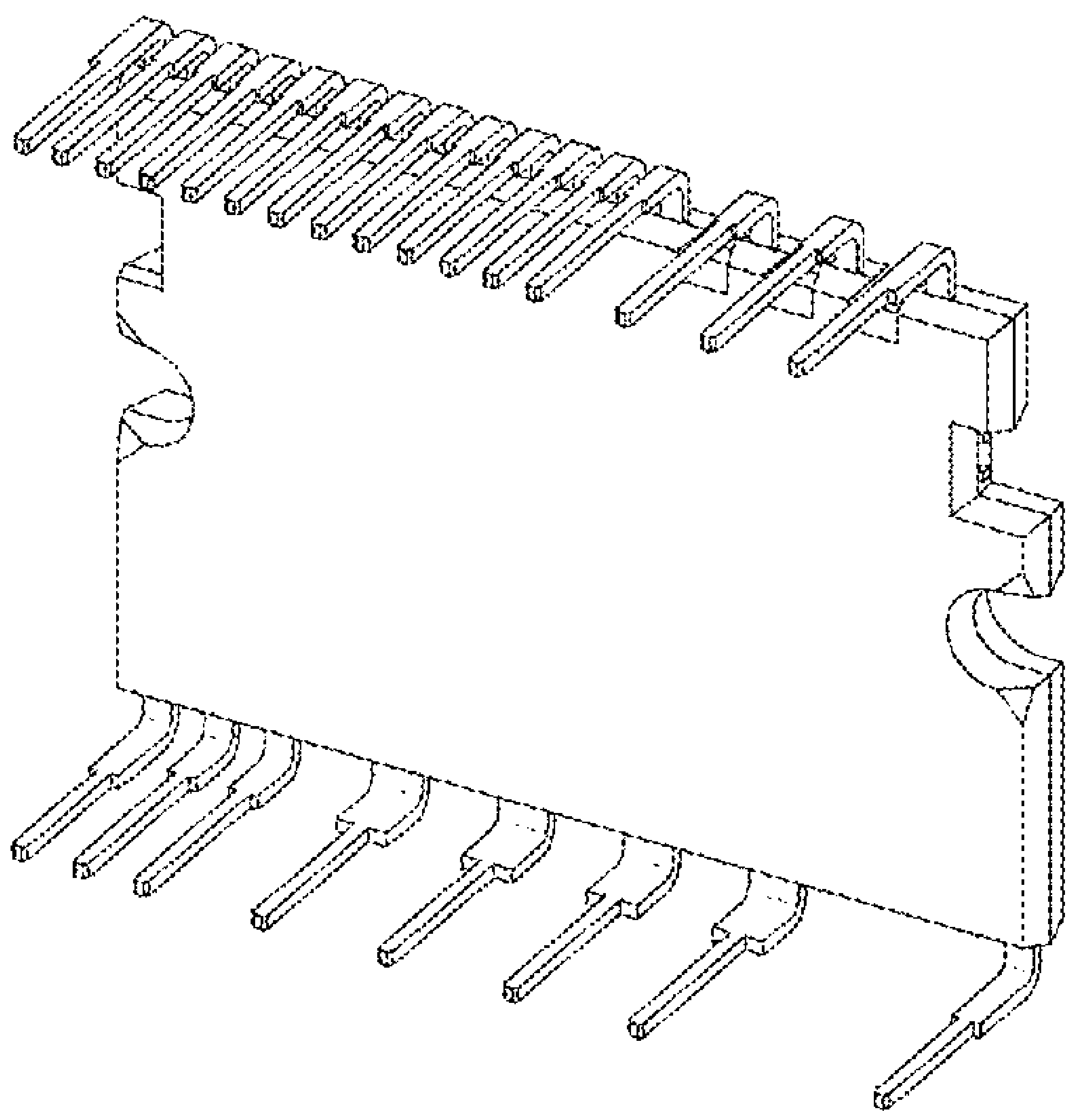
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a semiconductor device showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof,
FIG. **5** is a right side view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof; and,
FIG. **8** is a rear, top, and right side perspective view thereof.

1 Claim, 8 Drawing Sheets



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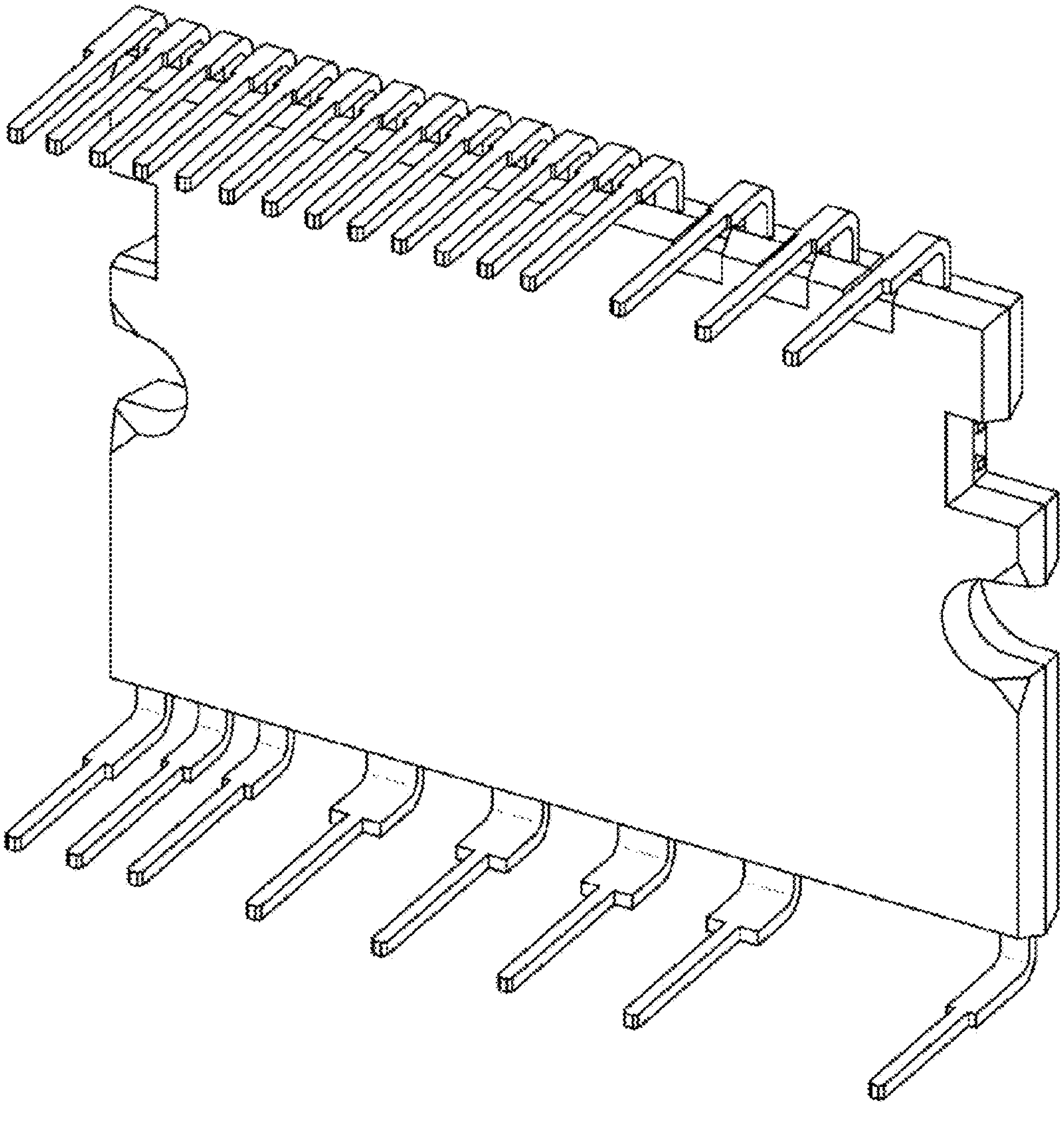

FIG. 1

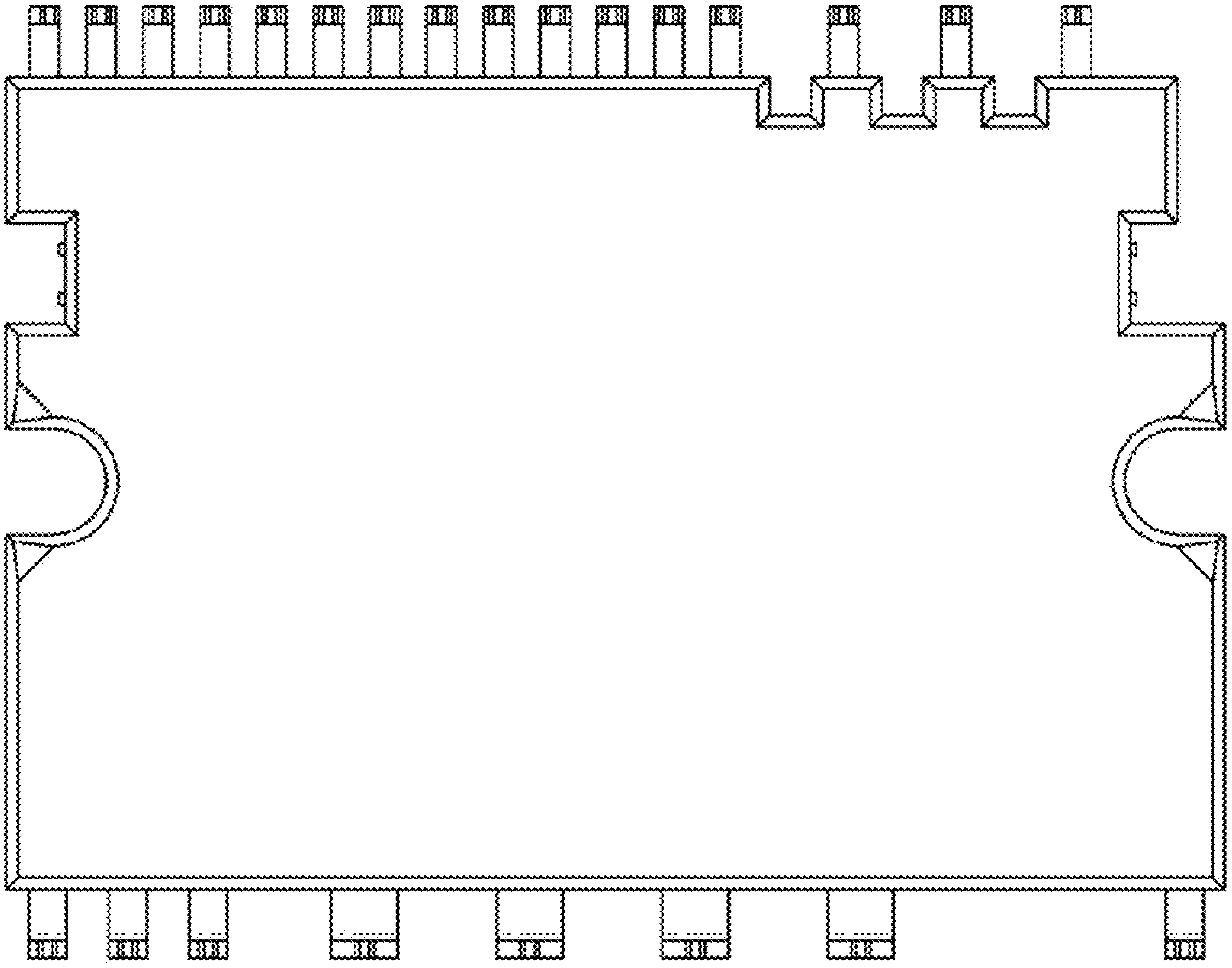

FIG. 2

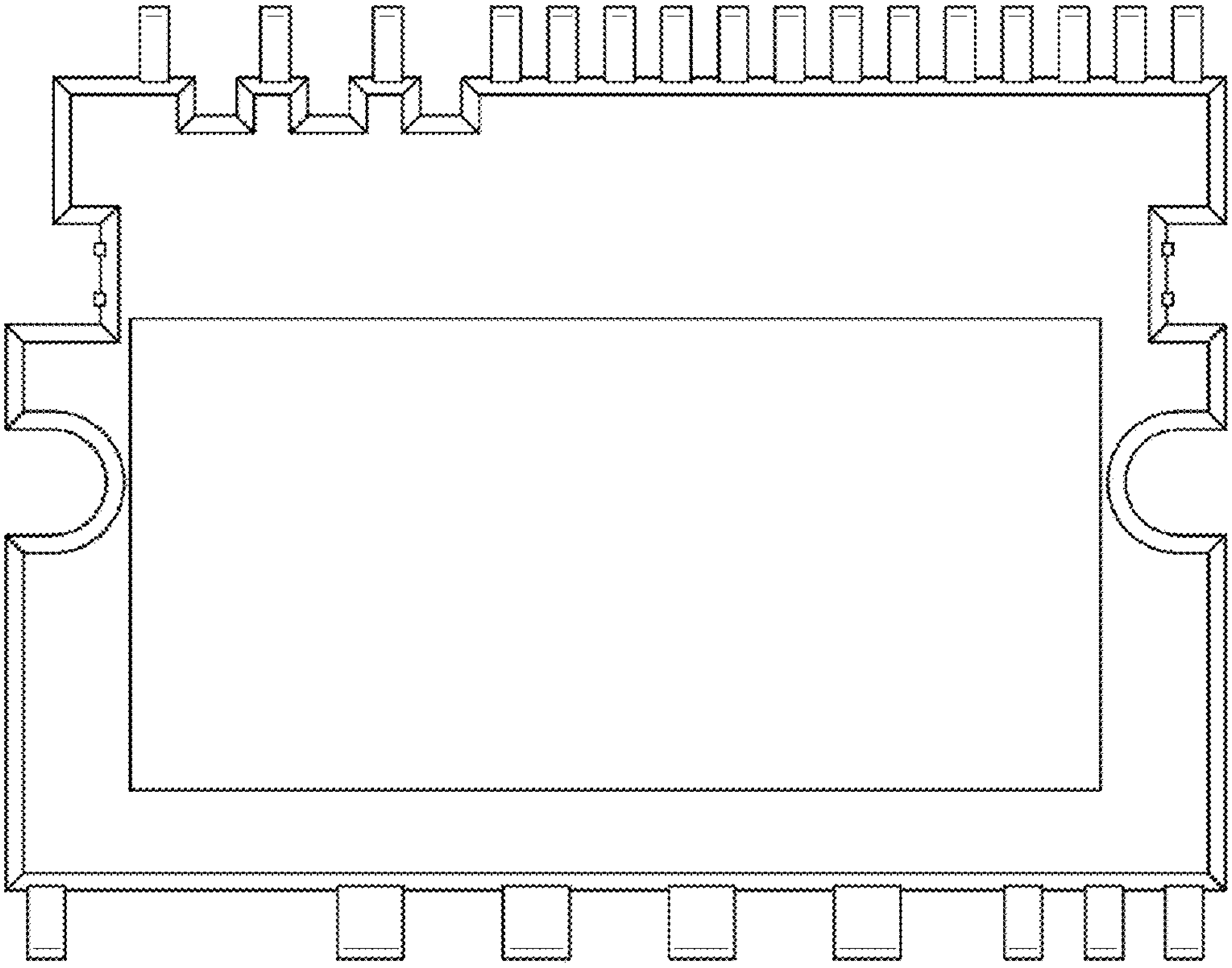

FIG. 3

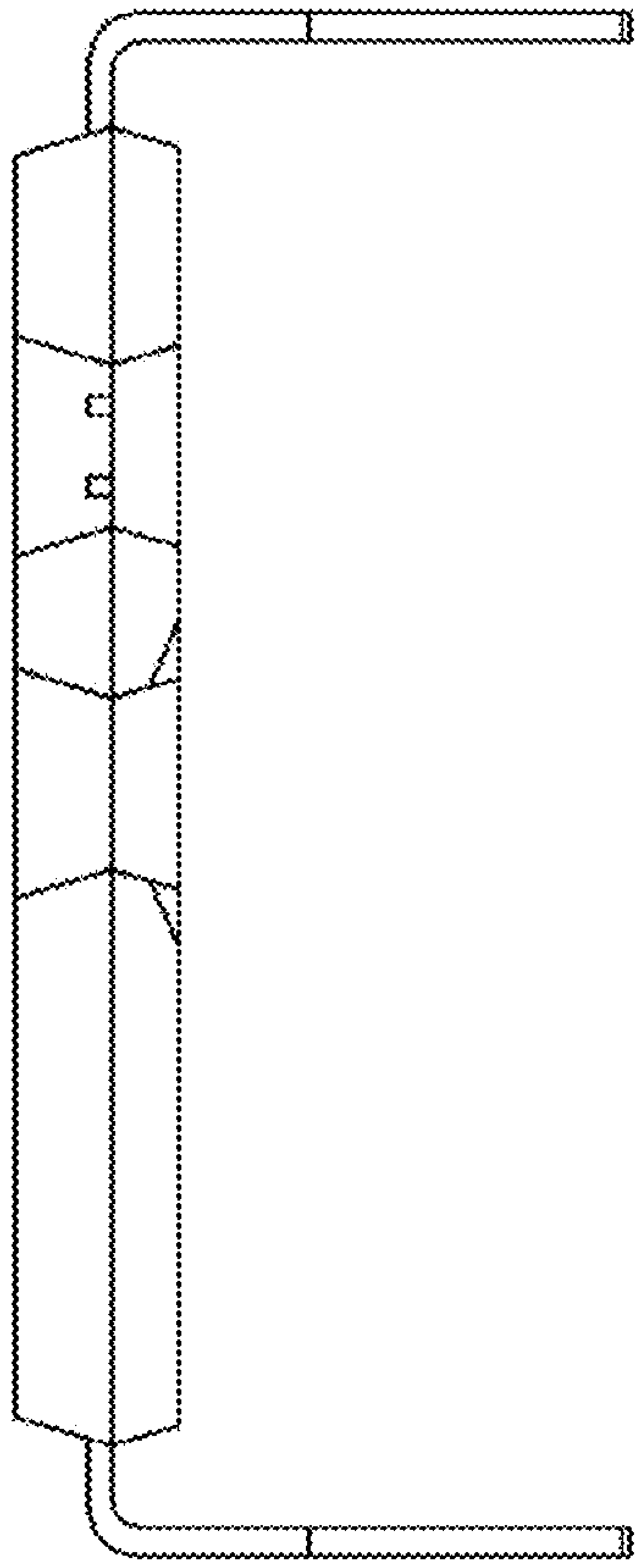

FIG. 4

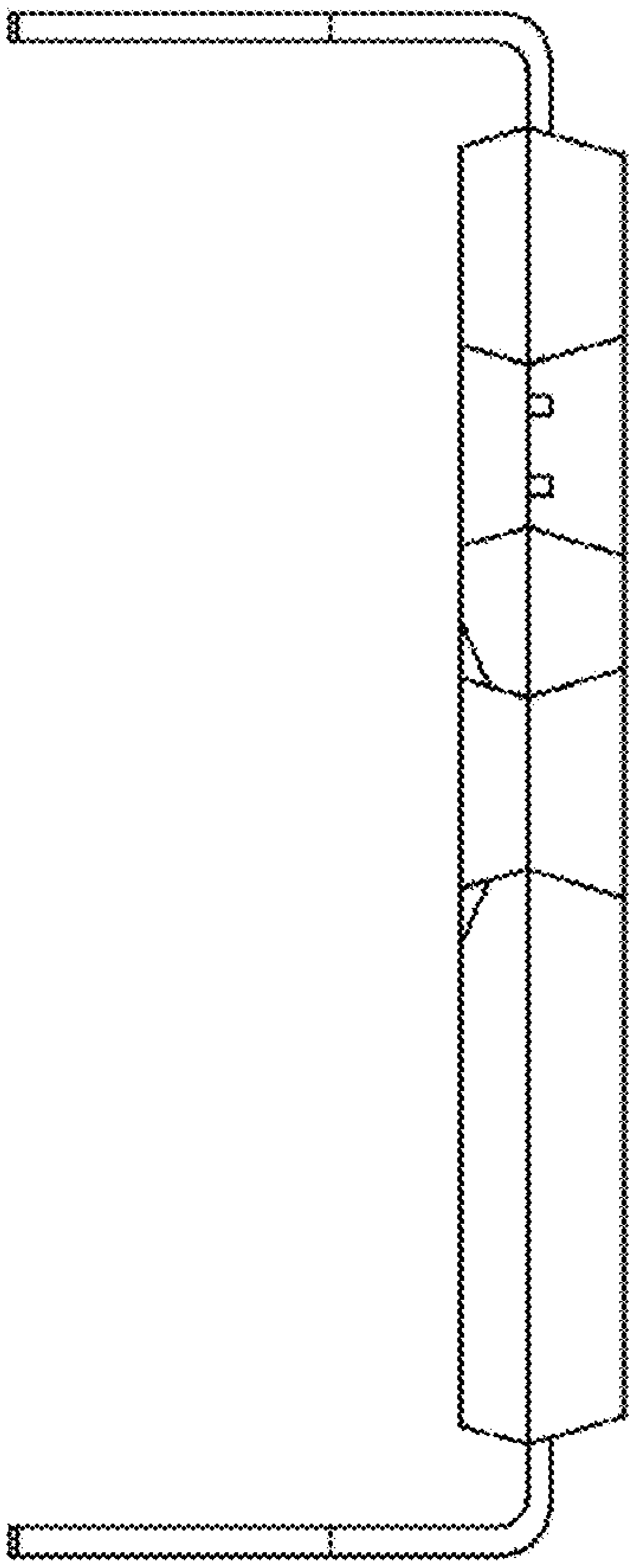

FIG. 5

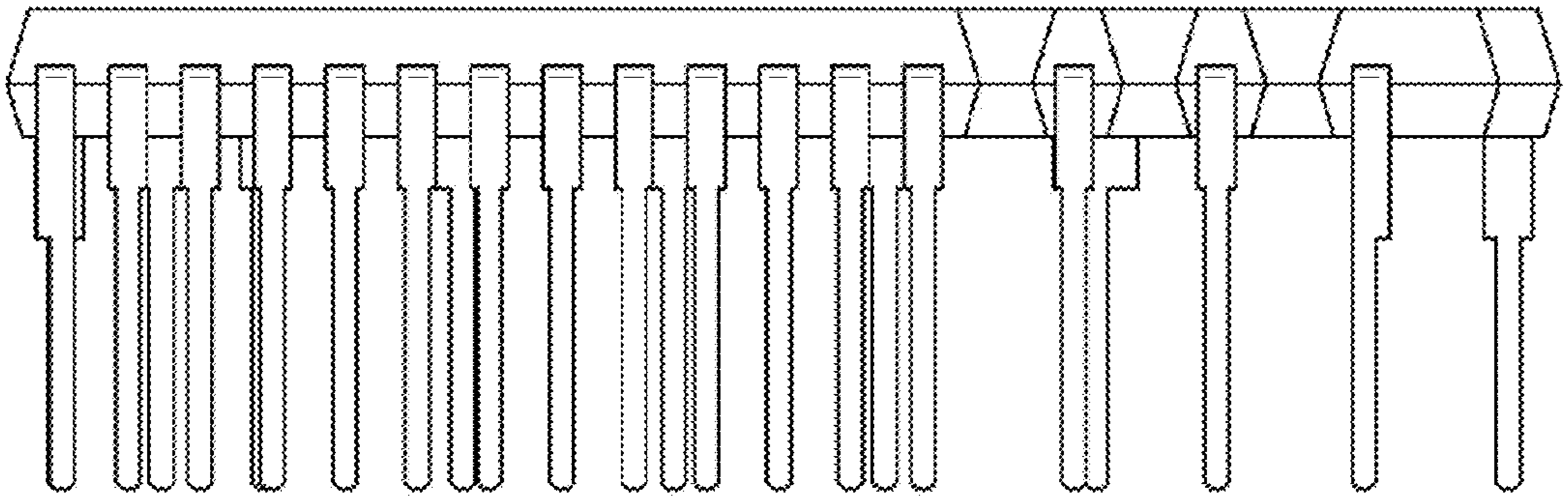

FIG. 6

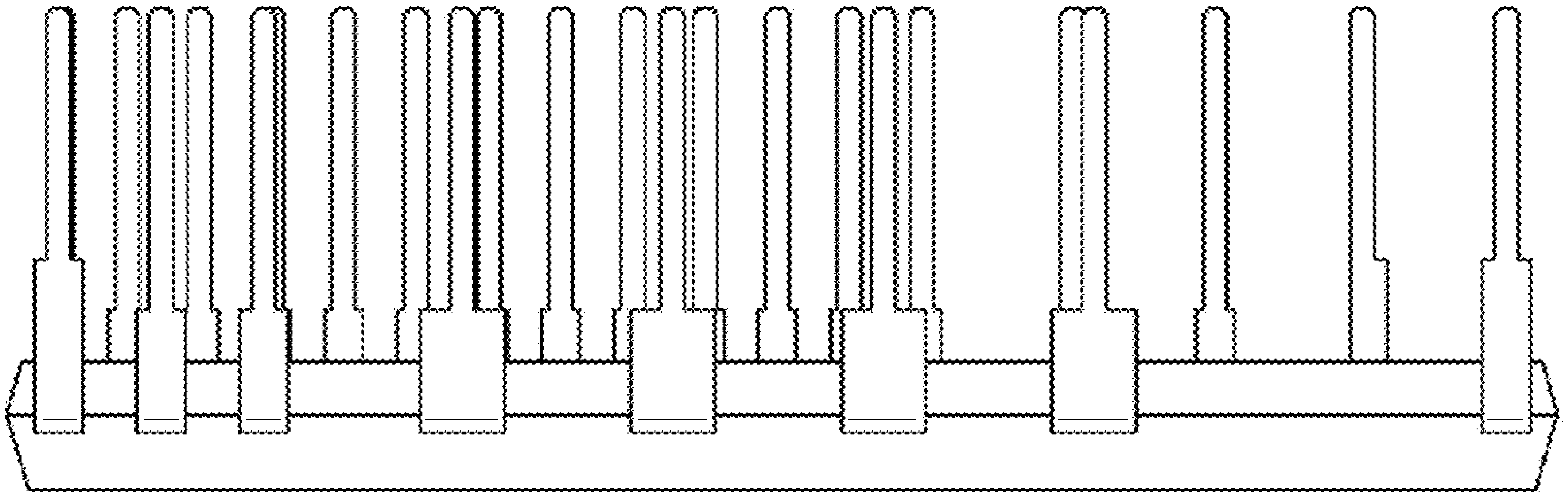

FIG. 7

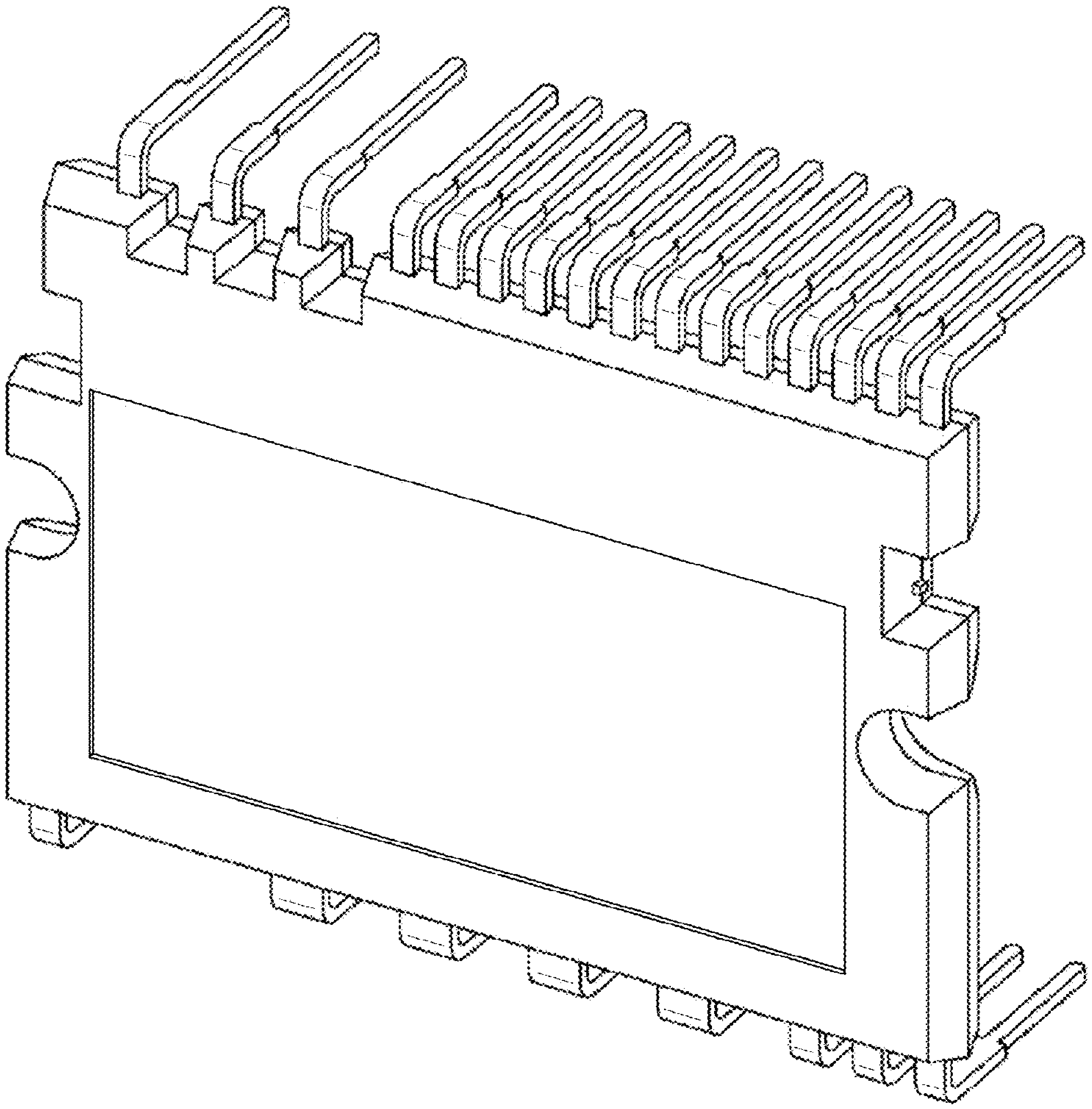

FIG. 8